



GaN Switches Will Dominate the Market

Chris Lee – Director of Product Marketing
Aug 6th 2020

GaN Switches Increase Efficiency of Offline Power Conversion

GaN Brings Increased Efficiency

- **GaN switches conduct via a two-dimensional electron-gas (2DEG)**

- ▶ Less impedance than traditional silicon channel structures

Technology	Normalized per Unit Area			Gate Voltage
	$R_{DS(ON)}$	C_{OSS}	Switch Transition Time	$V_{GS(ON)}$
Lateral Si MOSFET	1	1	1	~5 V
PowiGaN™ Switch	0.07	< 0.18	0.05 to 0.1	~5 V

- **GaN devices smaller and switch more efficiently for a given $R_{DS(ON)}$**

- ▶ Eliminates heatsinks, heat-spreaders, increases lifetime and reliability

- **GaN switching devices turn on/off very fast**

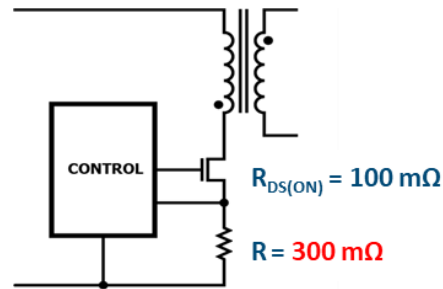
- ✓ Low switching loss
- ✗ High potential for EMI



Using GaN Switches is Challenging

■ Require optimized driver

- ▶ Uncontrolled fast switching can cause EMI problems
- ▶ Parasitics can cause VHF oscillation that can be destructive
 - Especially for discretely packaged GaN devices



■ External current sensing reduces the efficiency benefit

- ▶ Discrete designs use current sense resistors with $R_{DS(ON)} \geq \text{GaN switch!}$
 - Needed to provide sufficient voltage drop for fast current limit loop response

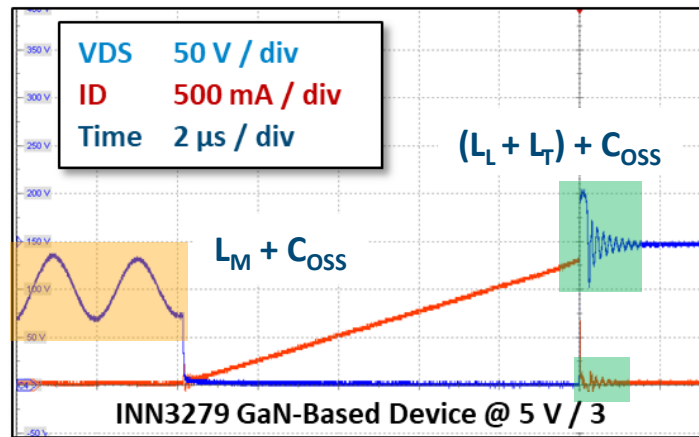
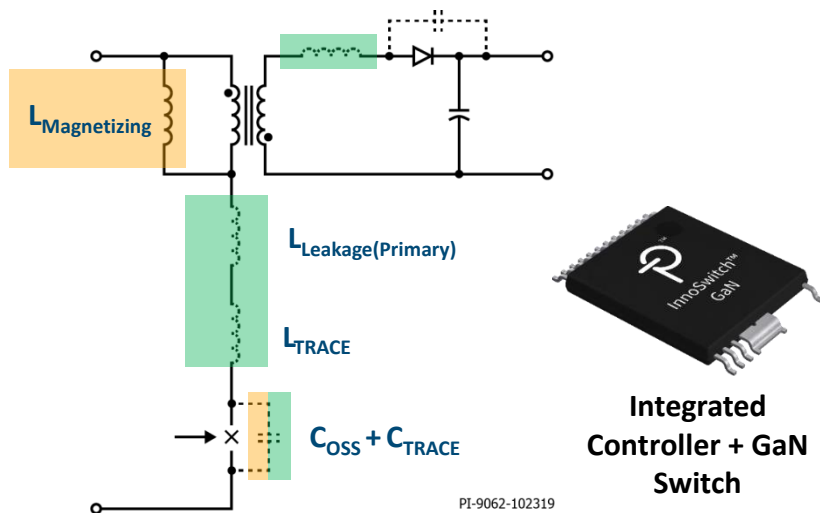
■ Continuous voltage rating $\geq 650\text{ V}$ is needed for reliable flyback operation

- ▶ Many HV GaN devices are rated at 480 V continuous – only good for HB circuits
- ▶ Voltage spikes due to parasitic inductance could be a problem even for HB circuits

Integrated Drive and Control Eliminates Switching Challenges

■ Fast GaN operation presents challenges for discrete implementation

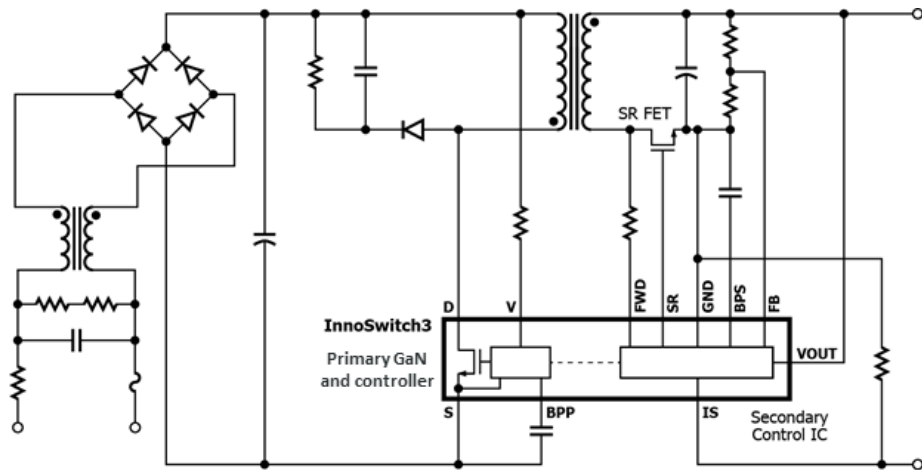
- ▶ Trace inductance plus fast switch transition will increase voltage stress and ringing
- ▶ Bringing control functions inside the device dramatically reduces trace inductance



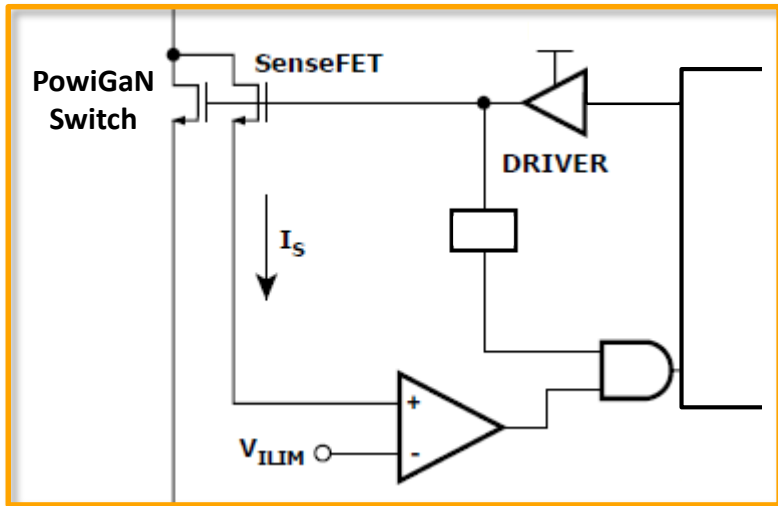
Integration greatly reduces resonant ringing in flyback switching (DCM shown)

InnoSwitch™3 Exploits GaN Efficiency and Eliminates Challenges

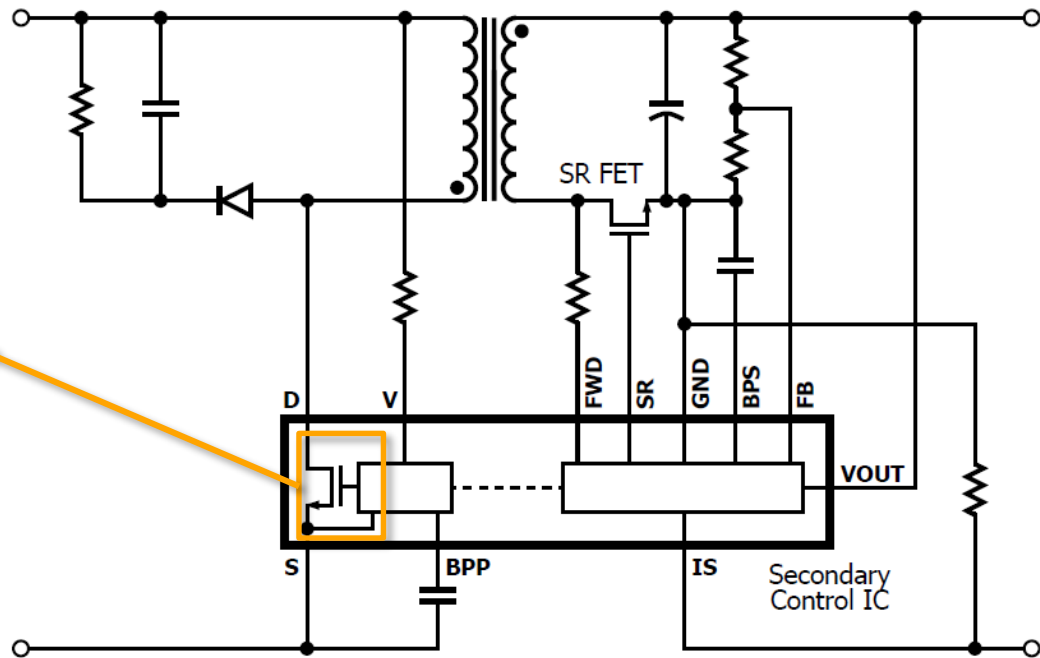
- **Driver matched to GaN switch**
 - ▶ Controls slew rate and di/dt
- **Allows integrated current limit**
 - ▶ Extremely fast control
 - ▶ No false triggering
- **Reduces parasitic components**
 - ▶ Less trace inductance
 - ▶ Reduced voltage transient spikes



Integrated Lossless Current Sensing Eliminates Series Resistors



SenseFET Technology allows lossless monitoring of drain current

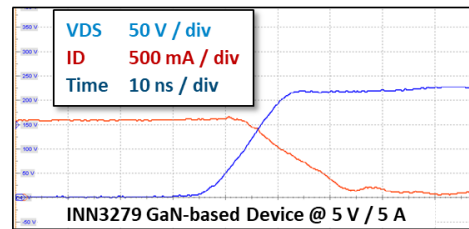
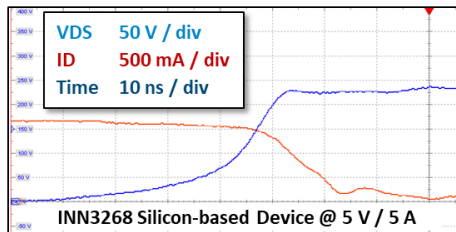


InnoSwitch3 simplified schematic

InnoSwitch3 Solves Fast Switching Challenges

■ Control of gate drive and circuit impedance via integration of driver stage controls switch transition rates

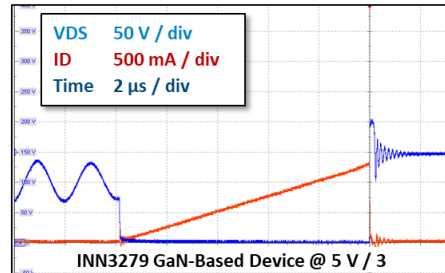
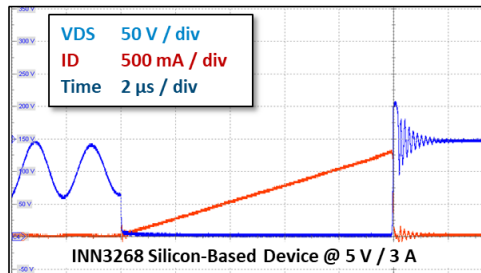
- ▶ Switch transition maximum slope same for silicon and GaN devices
- ▶ No special EMI issues for GaN
- ▶ Reduces fast di/dt voltage overshoot



Low-line CCM Turn-off Comparison ($100 V_{DC}$)

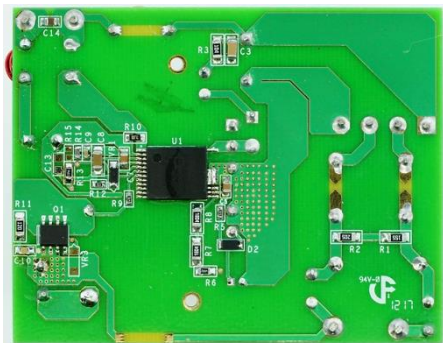
■ Integrated switch and control stage

- ▶ Optimized gate drive for each switch size
- ▶ Very accurate and fast SC/detection
- ▶ No external current sense elements
 - Reduces circuit losses
- ▶ Reduces circuit inductance and capacitance
 - Reduces voltage overshoot
 - No false-triggering of protection



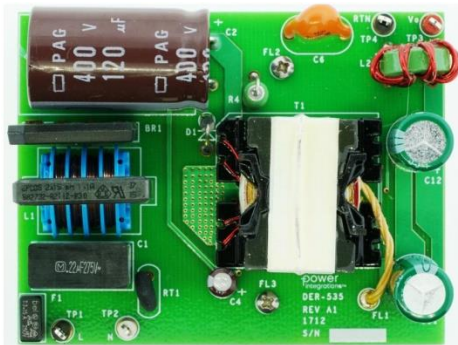
Low-line DCM Turn-on Comparison ($100 V_{DC}$)

InnoSwitch3 + PowiGaN = Highest Efficiency



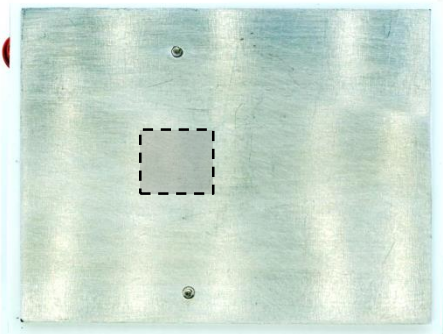
InnoSwitch3-CP
Size 8 MOSFET
(Requires large heat-spreader)

60 mm



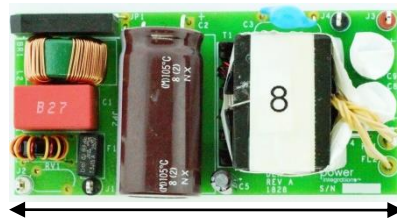
77 mm

DER-535
65 W 20 V / 3.25 A



Heat-spreader with outline of power device shown

InnoSwitch3-CP
Size 9 PowiGaN



35.5 mm

74.9 mm

DER-747
65 W 20 V / 3.25 A

PowiGaN is Winning in the Market

■ More GaN power devices shipped than anyone else

- ▶ Proprietary PI technology developed for power switching
- ▶ Cost-effective solution for increased efficiency requirements

■ Easy-to-use

- ▶ Integrated protection, drive and control eliminates challenges of discrete GaN
- ▶ Looks like a conventional part – easy to change between designs
- ▶ 750 V maximum operating voltage – ideal for offline flyback applications
- ▶ Very high reliability – more than 6 million shipped with no field failures



■ Provides major benefits across markets

- ▶ Smaller lighter power supplies
- ▶ Simplifies meeting existing and emerging energy standards
- ▶ Ideal for adapters, USB PD, industrial, and appliances

**No heatsinks makes open
frame /embedded power
more mechanically stable**

5 PI IC Families Already Feature PowiGaN Switches

■ Integrated GaN switch used across multiple families

- ▶ InnoSwitch3-EP
- ▶ InnoSwitch3-CP
- ▶ InnoSwitch3-Pro
- ▶ LYTSwitch™-6
- ▶ InnoSwitch3-MX



Designing for Smallest Size and Highest Efficiency

Design Considerations for Reducing Size

- **Minimize component count**
 - ▶ Integrated solution
- **Select the smallest-sized part that will do the job**
- **Optimize utilization of 3D space**
 - ▶ Multiple PCBs may help but consider cost
- **Iterate design to optimize performance**
 - ▶ Especially transformer parameters
- **Optimize efficiency**
 - ▶ Must eliminate the heatsink to achieve a compact design
- **Effective thermal management**
 - ▶ Reduce component stress to increase lifetime



DER-602: 100 W No Heatsink USB PD

How to Minimize Losses

- **GaN devices excel – PowiGaN is ideal for switching applications**
 - ▶ Lower conduction losses from very low $R_{DS(on)}$
 - ▶ Lower switching losses from very low device capacitance
- **Quasi-resonant switching**
 - ▶ Valley-switching reduces turn-on loss for primary switch
- **Current limit and switching frequency control losses**
 - ▶ Balance conduction loss and switching loss of primary switch
- **Transformer selection**
 - ▶ Selecting the right transformer can improve overall efficiency
 - ▶ Iterate design to optimize performance
 - ▶ Design tools simplify transformer optimization – take advantage of PI Expert/PI Xls
- **SR FET selection and optimization**
 - ▶ SR MOSFETs are already widely used – optimize timing to increase efficiency



Transformer Optimization is Critical

■ Design target

1. K_p close to 1
 - At low-line $K_p > 0.85$
2. Optimize by selecting lowest voltage rating SR FET
3. Minimize $V_{DS(PEAK)}$
4. Reduce secondary turns

■ High value of VOR improves design

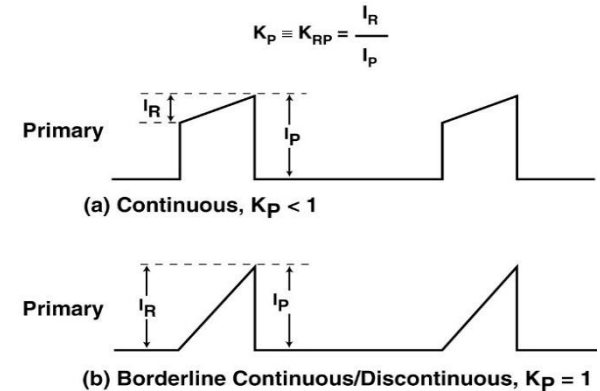
- ▶ Reduces duty-cycle especially at low-line
- ▶ Enables use of lower V_{DS} for SR MOSFET – reduces cost
- ▶ Easier to keep K_p close to 1 – enables valley-switching, to reduce switching loss and improve efficiency

■ Select operating frequency of 75 - 85 kHz

- ▶ Higher frequency reduces size of transformer
- ▶ Highest frequency increases switching loss
- ▶ Reduce frequency further if design is CCM ($K_p < 1$) will improve efficiency at low line

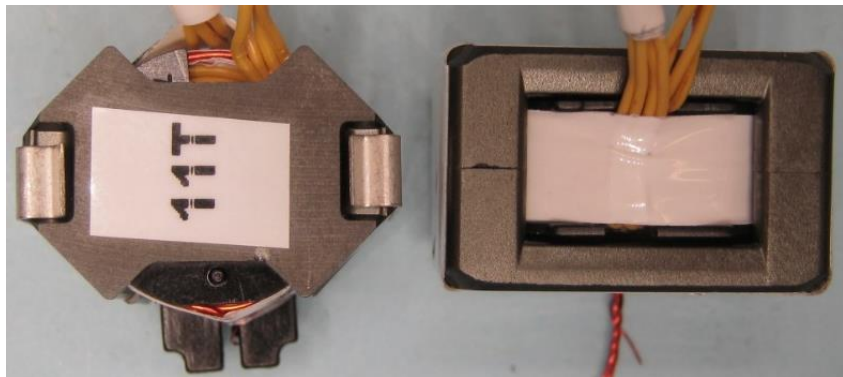
■ Minimize secondary number of turns

- ▶ Helps to reduce number of turns and also layers of primary winding
- ▶ Helps to reduce copper loss

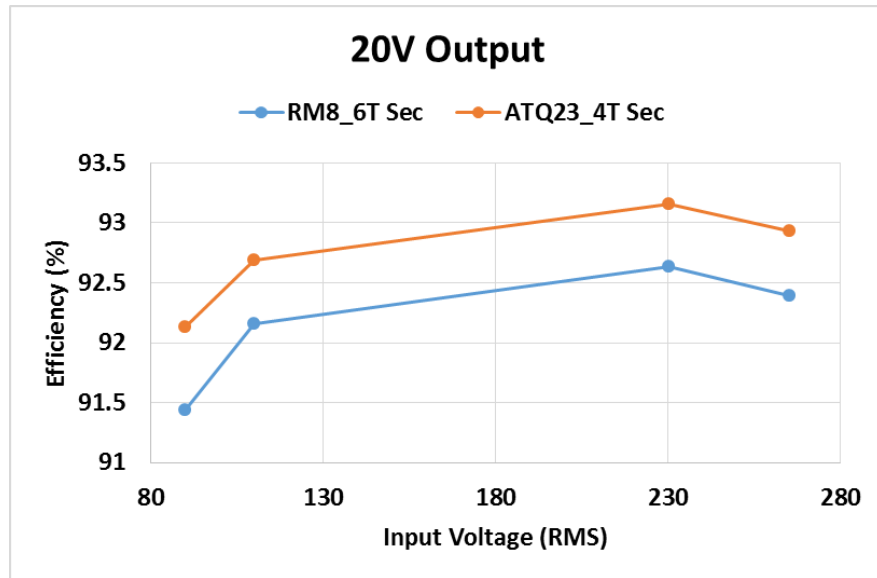


Select Core with Largest Area

RM8 vs. ATQ23.7/14



~38% bigger core area but fits in same space



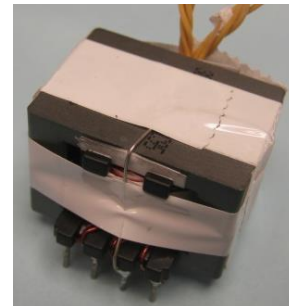
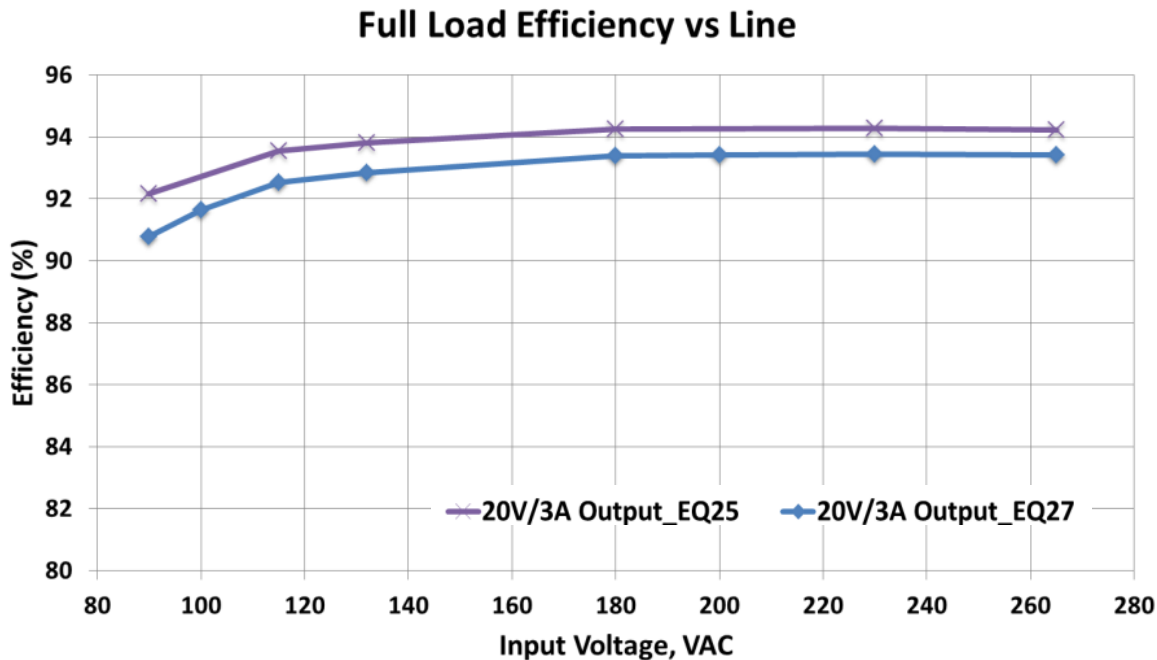
~0.7-0.8% efficiency improvement

45 W design results

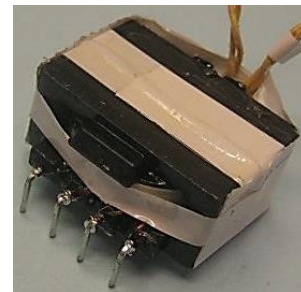
Look for Widest Bobbin Width

- Significant efficiency improvement with increased width

- ▶ 4.3 mm vs 8.1 mm



EQ25 Bobbin & Core



EQ2506/EQ27 Bobbin & Core

60 W design results

InnoSwitch Advantage

InnoSwitch3 Isolated Flyback Employs FluxLink™

Digital Feedback to Eliminate Optocouplers

Lossless Sensing

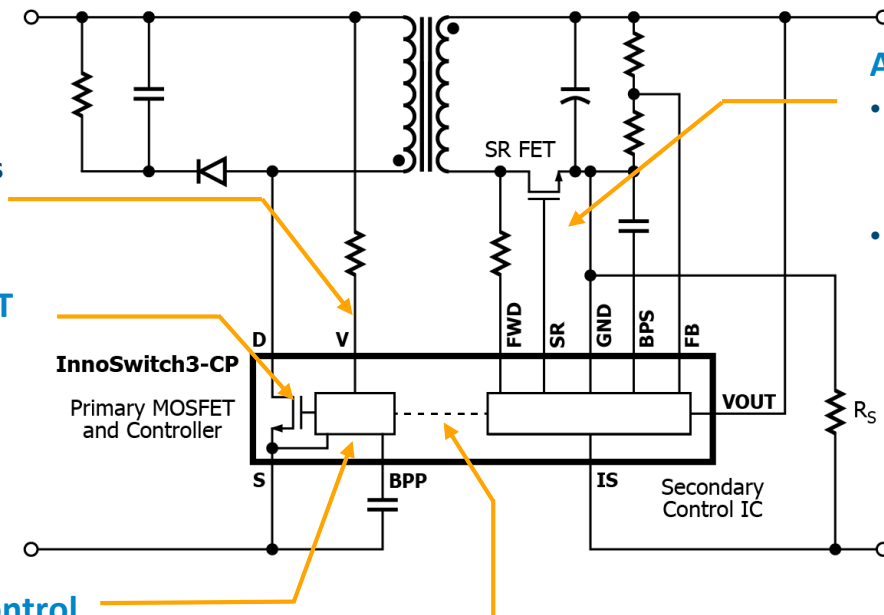
- Protection from line surges
- Adds < 2 mW to no-load

Integrated Power MOSFET

- 650 V / 725 V / 750 V

Proprietary Switch and Control

- CCM and Quasi-resonant switching
- Highest efficiency
- Lowest losses



FluxLink – Isolated Feedback

- High reliability, lifetime

Active Control of SR MOSFET

- Reduced diode conduction increases SR FET conduction time for best efficiency
- Seamless DCM-CCM transitions

Characteristic	Specification
Voltage Tolerance	± 3%
Current Tolerance	± 5%
Transient Response	Excellent
No-Load Input Power inc. line sense	< 15 mW

FluxLink Accurately Controls Power Conversion

- **Magneto-inductive coupling primary-to-secondary**

- ▶ Benefits of secondary-side control
- ▶ Simplicity of primary-side driver
- ▶ Isolation without optocouplers

- **Crosses isolation barrier**

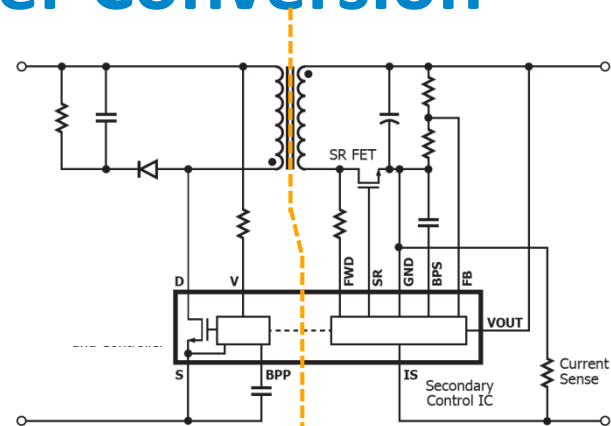
- ▶ Controls both primary and secondary switching
 - Optimizes performance for highest efficiency
- ▶ Meets all regulatory and hi-pot isolation requirements

- **Directly monitors output**

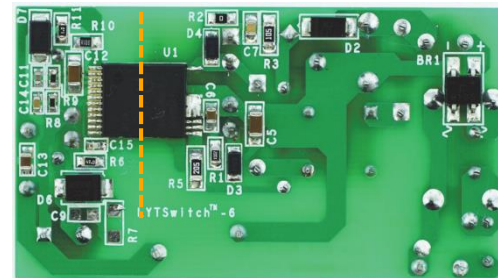
- ▶ Accurate output voltage and current

- **Drives synchronous rectification MOSFET**

- ▶ Simple design
- ▶ Highly reliable under all conditions



FluxLink: Magneto-inductive coupling crosses the isolation barrier



CQC, UL and TUV certified isolation as barrier component

InnoSwitch3 Family

InnoSwitch3 ICs with PowiGaN Technology

Achieve >100 W

- InnoSwitch3 silicon transistors are highly effective up to 65 W
- PowiGaN switches provide more power
 - ▶ Lower $R_{DS(ON)}$ per unit area
 - ▶ Lower switching losses
- PowiGaN devices
 - ▶ InnoSwitch3-CP – constant power
 - ▶ InnoSwitch3-EP – for open-frame
 - ▶ InnoSwitch3-Pro – digital control

725 / 750 V Part Number	230 VAC +/- 15%		85 - 264 VAC	
	Adapter	Open Frame	Adapter	Open Frame
INN3x74C	20 W	25 W	15 W	20 W
INN3x75C	25 W	30 W	22 W	25 W
INN3x76C	35 W	40 W	27 W	36 W
INN3x77C	40 W	45 W	36 W	40 W
INN3x78C	70 W	75 W	55 W	65 W
INN3x79C	80 W	85 W	65 W	75 W
INN3x70C	90 W	100 W	75 W	85 W

PowiGaN switches

PowiGaN Delivers Best Performance

- **Highest efficiency conversion**

- ▶ 95% efficient – flat across line and load
- ▶ No heatsinks
- ▶ Highest power density for smart-charging adapters

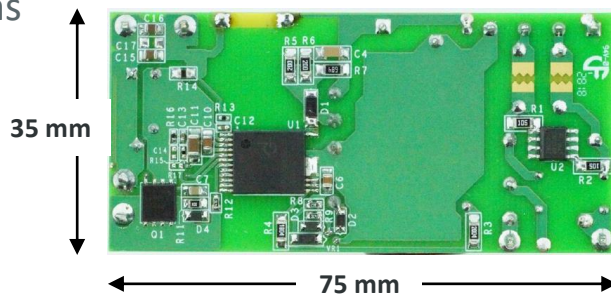


- **Safe, familiar, reliable – it just works**

- ▶ Just another switching technology from Power Integrations
- ▶ Looks and behaves like a silicon MOSFET
- ▶ No EMI challenges
- ▶ High operating voltage and increased surge margin
- ▶ Less than 40 mW no-load consumption at 265 VAC

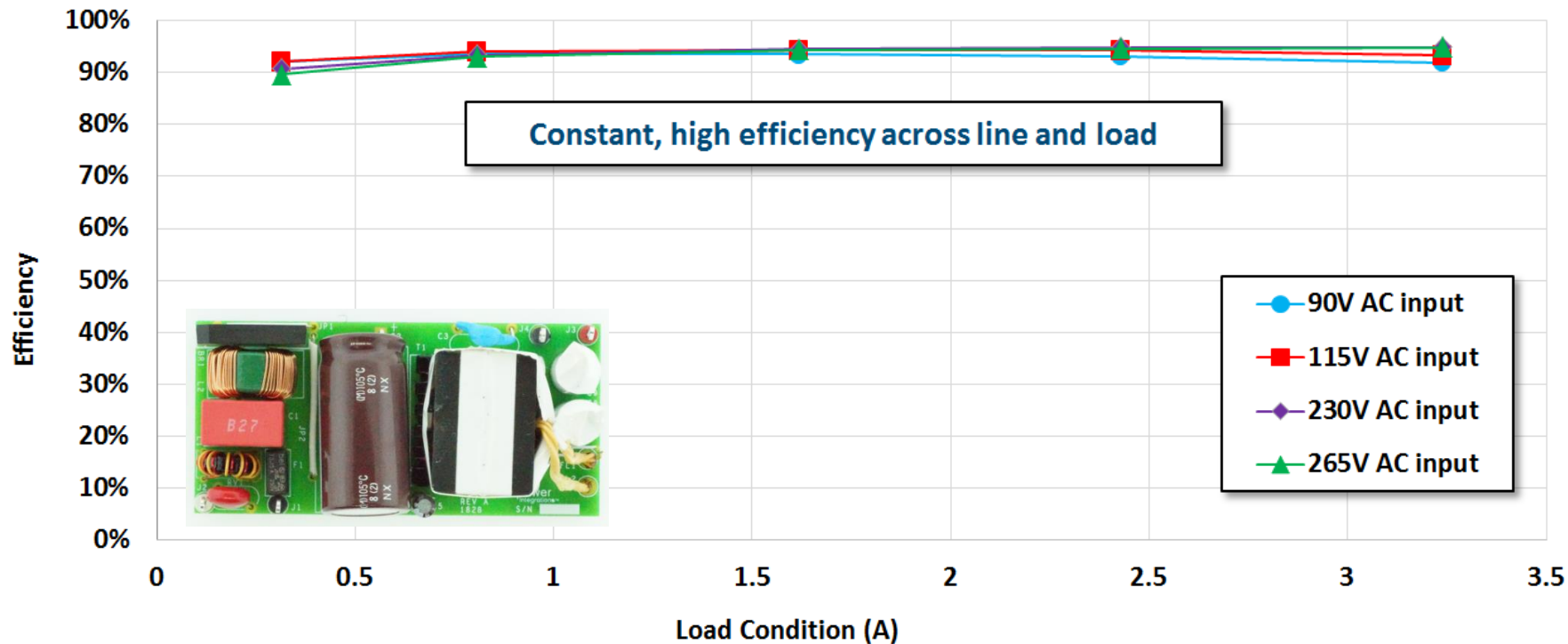
- **In production now**

- ▶ More than 6 million parts shipped-to-date



DER-747
65 W 20 V / 3.25 A

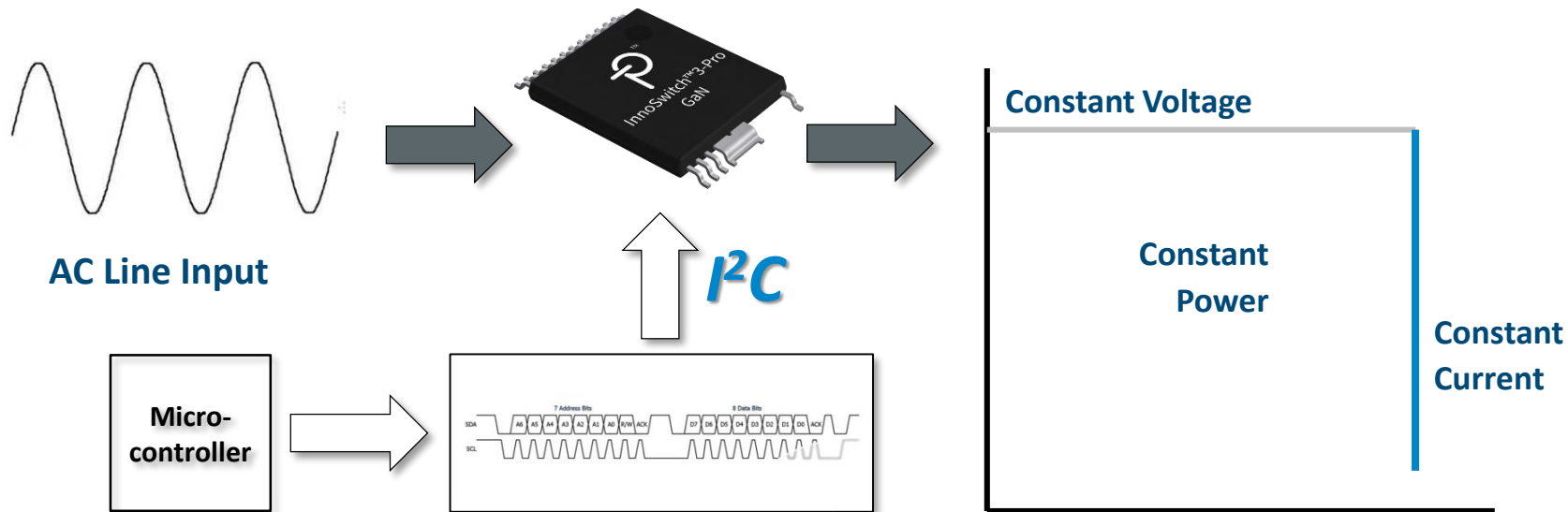
65 W DER-747 PowiGaN Constant High Efficiency Across Line and Load



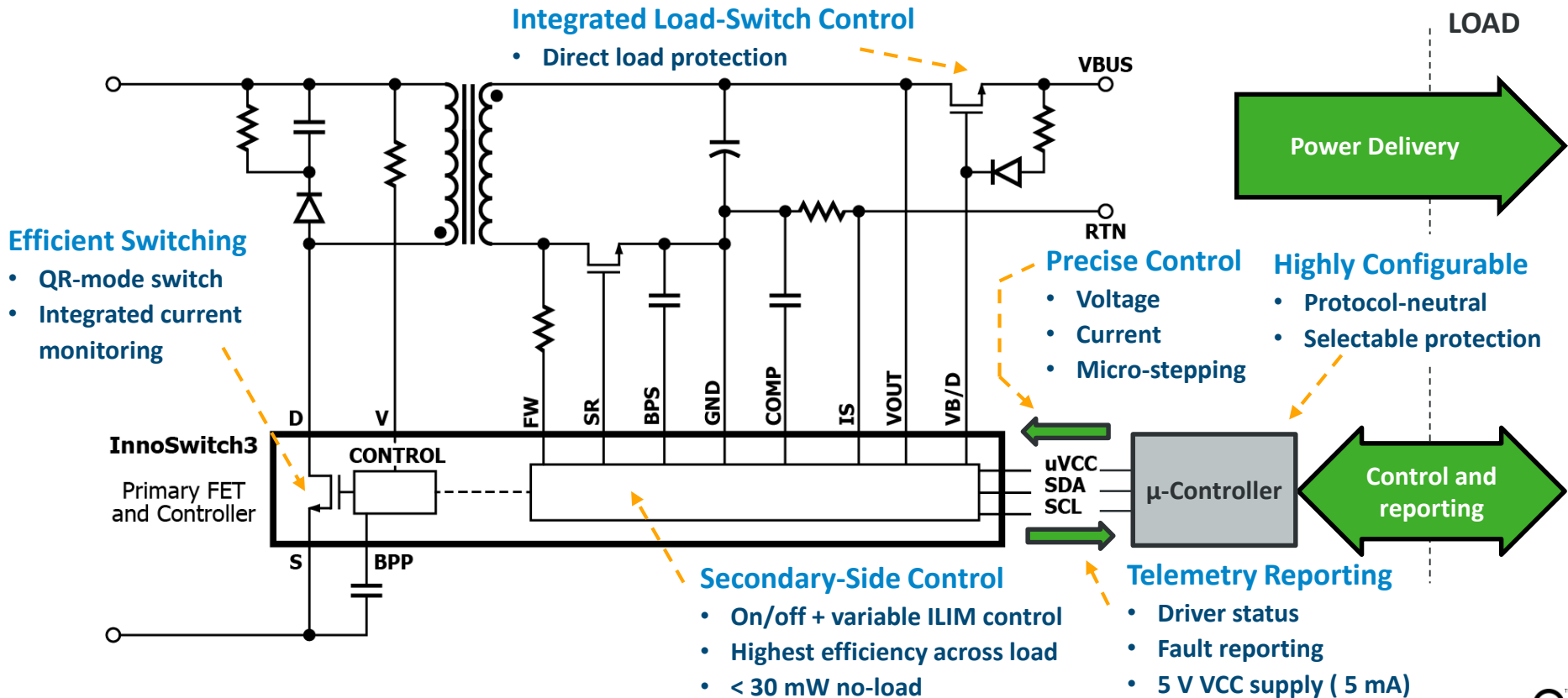
InnoSwitch3-Pro: Digitally Programmable Power Conversion

■ Advanced control engine with digital interface (I²C)

- ▶ Output voltage and current control – CV/CC/CP output characteristic
- ▶ Configurable protection – enable/disable, shutdown/auto-restart, trigger-points



Adding Output Control to InnoSwitch3



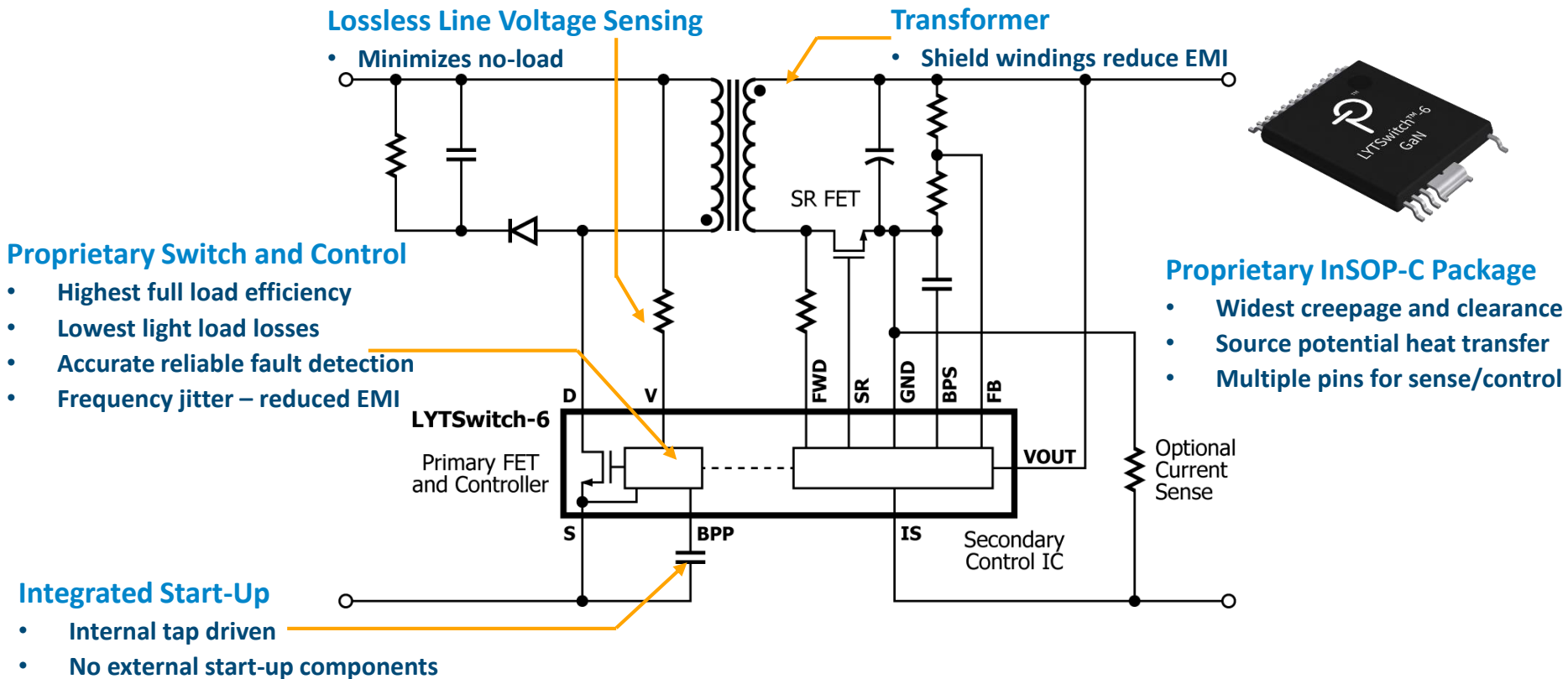
InnoSwitch3-Pro Supports a Wide Range of Applications

- **Any dynamic rapid-battery-charging protocol**
 - ▶ Smart phones, notebooks/laptops/tablets, smart speakers
 - ▶ USB PD 3.0 + PPS “load-directed” charging protocol
 - ▶ Supports all rapid charge protocols including USB PD, Rapid Charge
- **Field-programmable and region-centric protection**
 - ▶ Multi-voltage lighting ballasts, DIN-rail power supplies
 - ▶ Protection features that match regional preferences
- **Programmable performance in non-charging applications**
 - ▶ Multiple solutions from single power supply design
 - ▶ Reduces design-time, reduces production, approvals and inventory costs



LYTSwitch-6

LYTSwitch-6 High Efficiency Versatile Ballast Designs



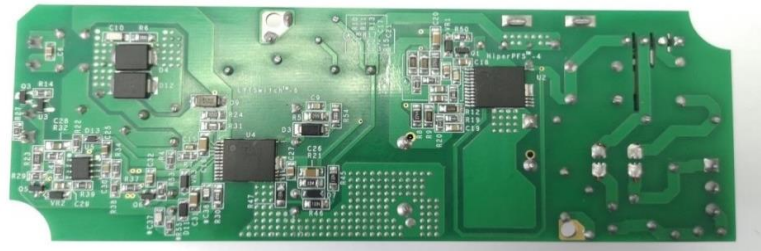
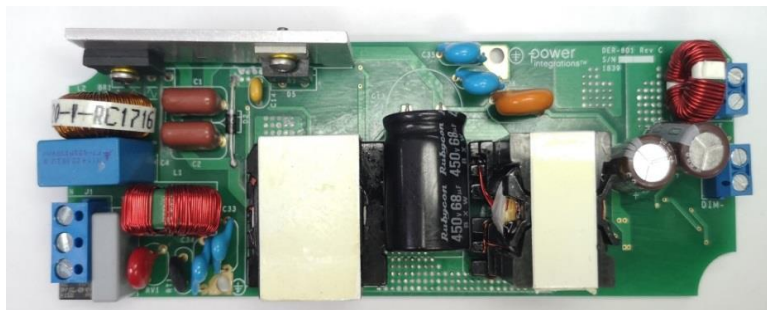
DER-801: 100 W Wide-Range Ballast

■ Features

- ▶ Constant voltage and constant current mode LYTSwitch-6 (LYTSwitch-6079C)
- ▶ 90-305 VAC and active PFC with HiperPFS-4
- ▶ 3-in-1 dimming (0-10 V, PWM and resistor)
 - Dimmable to 1% and dim-to-off
- ▶ Low component count
- ▶ Flicker-free operation

■ Typical Specification

- ▶ Output voltage: 48 V
- ▶ Output current: 2080 mA
- ▶ Output ripple current: <5% of nominal
- ▶ Efficiency: >90% at 230 VAC
- ▶ Power factor: >0.9 at full-load
- ▶ Surge withstand: 2.5 kV differential

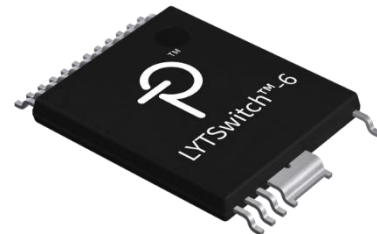


LYTSwitch-6: Provides Best Performance

- **$\pm 3\%$ CV and CC output characteristic**
 - ▶ Single design covers multiple applications
- **Low no-load <15 mW (without PF)**
 - ▶ Easily meets DOE-6 and ENERGY STAR® for North America
- **Supports analog and PWM dimming**
- **Very high efficiency**
- **Fast control reduces output ripple**
 - ▶ Less output capacitance required
- **Excellent load regulation and instantaneous transient response**
 - ▶ Ideal for multi-string applications, such as RGB with highly variable independent loads

Expanding the LYTSwitch-6 Power Range

Part Number	MOSFET $V_{DS(max)}$	Output Power - Open Frame		
		277 VAC ($\pm 15\%$)	90-305 VAC	380 - 450 VDC
LYT6063C	650 V	15 W	12 W	
LYT6073C	725 V			25 W
LYT6065C	650 V	30 W	25 W	
LYT6075C	725 V			40 W
LYT6067C	650 V	50 W	45 W	
LYT6077C	725 V			60 W
LYT6068C	650 V	65 W	55 W	
LYT6078C	750 V	75 W	65 W	90 W
LYT6079C	750 V	85 W	75 W	100 W
LYT6070C	750 V	95 W	85 W	110 W



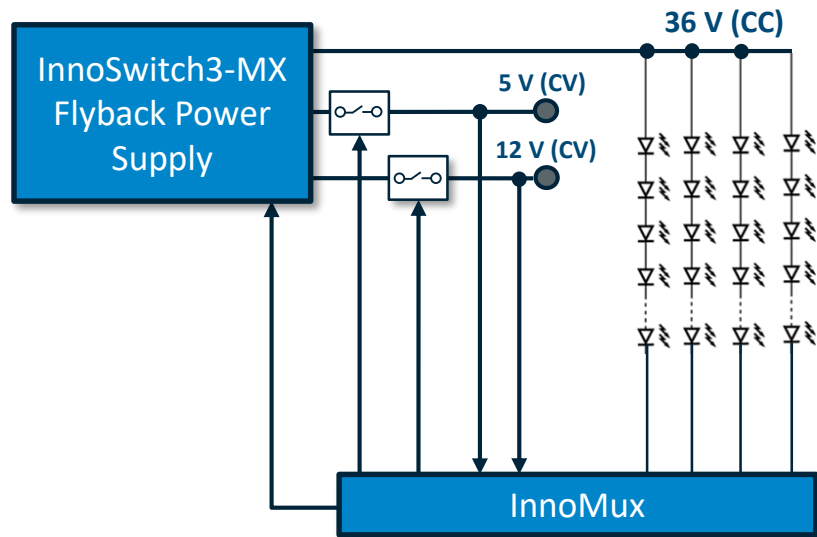
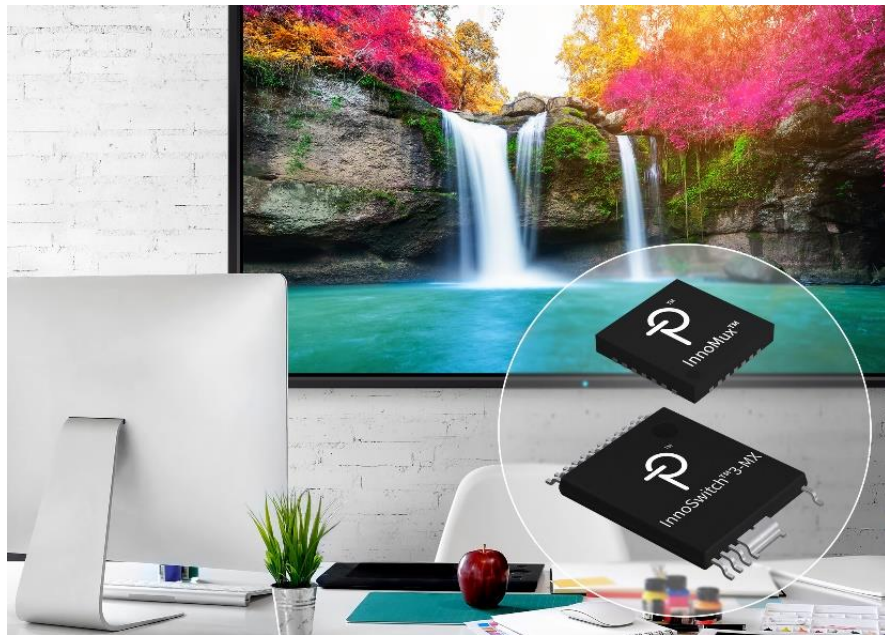
Advanced InSOP-24 package

- Reduced board space
- No heatsinks required
- Extended creepage and clearance

PowiGaN

InnoSwitch3-MX

InnoMux™ – Single-Stage Structure for Display Applications

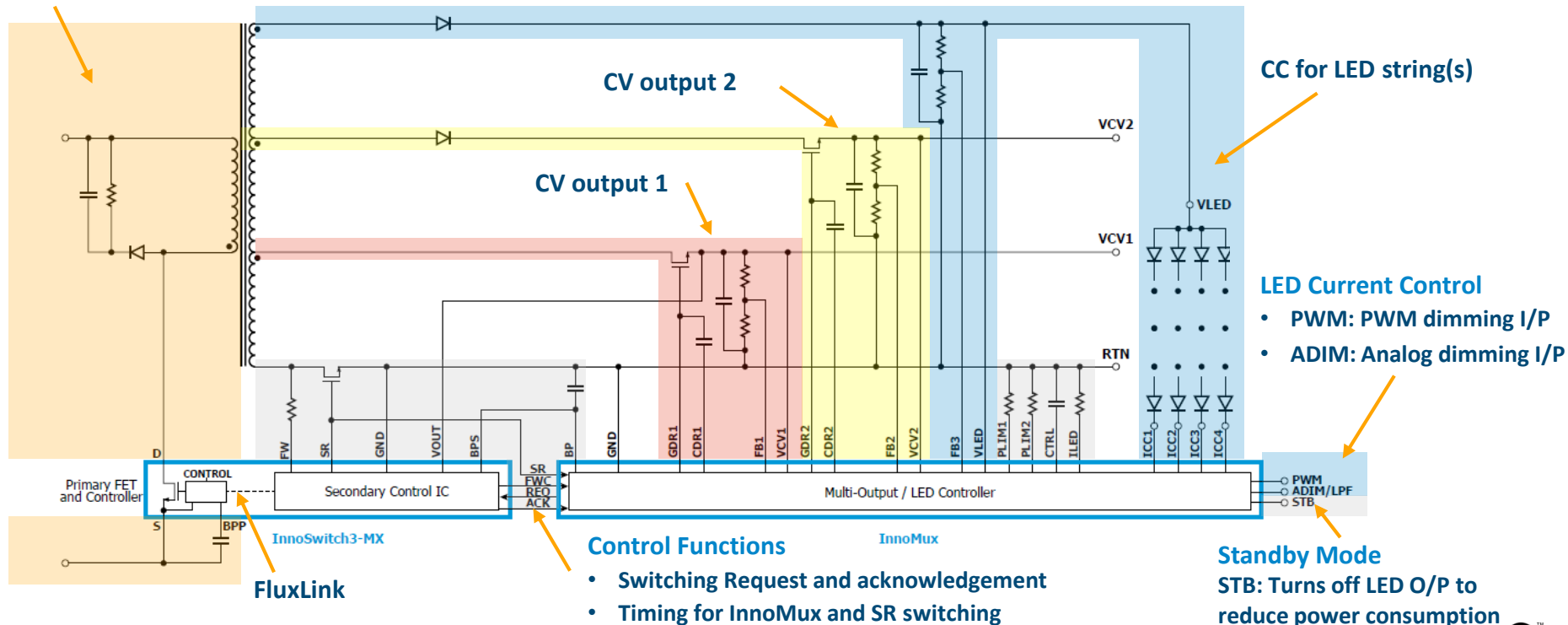


InnoSwitch3-MX Plus InnoMux Single-Stage Conversion Provides CV and CC Outputs

InnoSwitch3-MX Provides Power When Required

InnoMux IC Sends it Only Where Needed

Primary-side switching



InnoMux Chipset Provides Up to 75 W Output

InnoSwitch3-MX

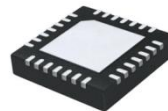
Part Number	Primary MOSFET (V _{DS(MAX)})	Power (W) 85 – 264 VAC
INN34X5C	650/725	20
INN34X6C	650/725	25
INN34X7C	650/725	32
INN3468C	650	40
INN3478C	750	55
INN3479C	750	65
INN3470C	750	75



InSOP-24D (C-Package)
MSL-3 rated – wave solder and reflow

InnoMux

Part Number	Channels		Package
	LED strings	CV O/Ps	
IMX101J	1	1	QFN
IMX101U	1	2	HSOP
IMX102U	4	1	HSOP



QFN-28 (J-Package)
MSL-1 rated – reflow



HSOP-28 (U-Package)
MSL-1 rated – wave solder

Reference Design	Typical Application	Input (VAC)	Power (W)	Part Number		O/P 1 Const. Voltage	O/P 2 Const. Voltage	O/P 3 Const. Current	Dimming
				InnoSwitch3-MX	InnoMux				
DER-636	Monitors	90 - 264	40	INN3468C	IMX102U	5 V @ 3 A	-	36 V @ 0.6 A	PWM/Analog



power.com

